

To whom it may concern

Conversion of ISIG process to EPIG or DIG

Dear Valued Customer

The purpose of this letter is to inform you that the ISIG process will be stopped at Hofstetter PCB AG. As a replacement, we introduced DIG more than 3 years ago and as an alternative there is also the nickel free final surface available at Hofstetter with Palladium and Gold, called EPIG. With those 2 options we can still fulfil the market requirements regarding nickel free final surfaces as both of them are solderable and Au-wire bondable. Time of stopping is December 31, 2022. Last orders for the ISIG process have to be placed at the beginning of December 2022.

The ISIG final surface has been increasingly replaced since the introduction of the DIG process. It has only been requested on a very small scale in the past few years. In addition, experiences of the last 3 years have shown that the DIG and also the EPIG process work more reliable. All of this has forced us to finally stop the ISIG process and to concentrate fully on the other two options.

Overall information about the 2 nickel free DIG and EPIG final finishes:

1. There is no guarantee that the processes are running each day. Under normal circumstances both processes are running 3 days a week in the minimum.
2. The 2 processes have their limitations regarding the processability with different materials. Therefore we highly recommend to test the material or a specific layout before we run the article in high volumes. The past has shown us that this can be very important and helpful to react at an early stage.
3. For the EPIG process, Plasma Cleaning is highly recommended and without special notice, we will always run a Plasma Cleaning before the finish. High volumes can be tested to run without this extra process. Overall Hofstetter PCB AG reserves the right to carry out a pre-treatment without consultation in case of small quantities.
4. Please always keep in mind that the copper process and the copper structure will be visible and after the finish it will be even more visible. The copper process and the copper structure can have an influence to the assembly process, especially wire bonding is influenced by the copper structure underneath. Please contact us if you have questions regarding this topic.

HOFSTETTER

PCB PLATING

In the life of PCB manufacturing, EPIG and DIG are still very new processes. We are here to help you getting the best result out of these new final finishes. But the handling is and must be different if you compare it to ENIG or other final finishes which are on the market for decades. The handling starts already at the copper process and the solder mask processes.

Best Regards
Hofstetter PCB AG



Andy Stütz
CEO



Remo Fischer
COO/CTO